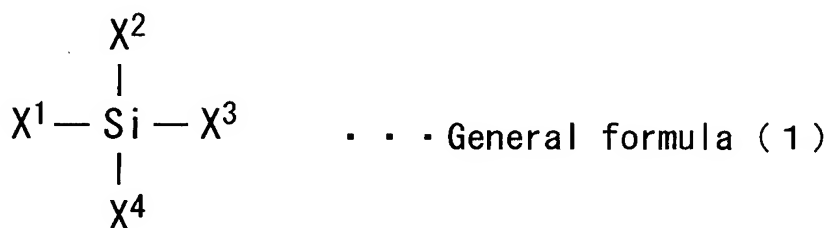


Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) An adhesive comprising a resin component, a metal chelate, and a silane coupling agent,

wherein said resin component includes a thermosetting resin and said silane coupling agent is composed of a silane compound represented by general formula (1):



wherein at least one of substituents X^1 through X^4 is an alkoxy group, and wherein if one or more of the substituents X^1 through X^4 is a substituent other than alkoxy group, such substituent other than alkoxy group is a substituent that includes in its structure a functional group selected from the group consisting of epoxy ring, vinyl group, amino group, mercapto group and methyl group, and

wherein the metal chelate is microcapsulated.

2. (Original) The adhesive according to claim 1, wherein said alkoxy group is a methoxy group.

3. (Original) The adhesive according to claim 1, wherein said alkoxy group is an ethoxy group.

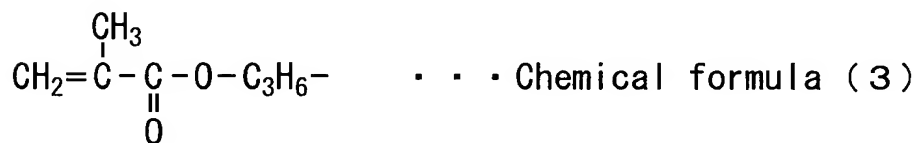
4. (Original) The adhesive according to claim 1, wherein at least one of the substituents X^1 through X^4 of said silane compound is a substituent other than alkoxy and at least one of said substituents other than alkoxy has an epoxy ring.

5. (Original) The adhesive according to claim 1, wherein at least one of the substituents X^1 through X^4 of said silane compound is a substituent other than alkoxy and at least one of said substituents other than alkoxy has an vinyl group.

6. (Original) The adhesive according to claim 4, wherein said substituent having the epoxy ring is a γ -glycidoxypropyl group represented by chemical formula (2):



7. (Original) The adhesive according to claim 5, wherein said substituent having the vinyl group is a γ -methacryloxypropyl group represented by chemical formula (3):



8. (Original) The adhesive according to claim 1, wherein an amount of said metal chelate is from 0.1 parts by weight to 20 parts by weight with respect to 100 parts by weight of said resin component and an amount of said silane coupling agent is from 0.1 parts by weight to 35 parts by weight with respect to 100 parts by weight of said resin component.

9. (Original) The adhesive according to claim 1, wherein said resin component includes a thermoplastic resin and an amount of said thermoplastic resin is 10 parts by weight or more with respect to 100 parts by weight of said thermosetting resin.

10. (Original) The adhesive according to claim 8, wherein said resin component includes a thermoplastic resin and an amount of said thermoplastic resin is 10 parts by weight or more with respect to 100 parts by weight of said thermosetting resin.

11. (Original) The adhesive according to claim 1, wherein said thermosetting resin is an epoxy resin.

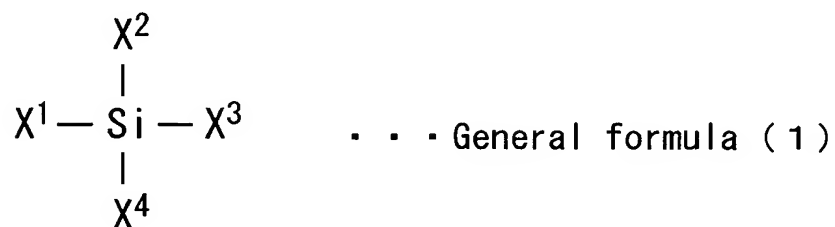
12. (Original) The adhesive according to claim 11, wherein the epoxy resin is an alicyclic epoxy resin.

13. (Original) The adhesive according to claim 1, wherein said metal chelate includes an aluminum chelate as a major constituent.

14. (Original) The adhesive according to claim 8, wherein said metal chelate includes an aluminum chelate as a major constituent.

15. (Currently Amended) An adhesive film obtainable by forming an adhesive into a sheet, the adhesive comprising a resin component, a metal chelate, and a silane coupling agent,

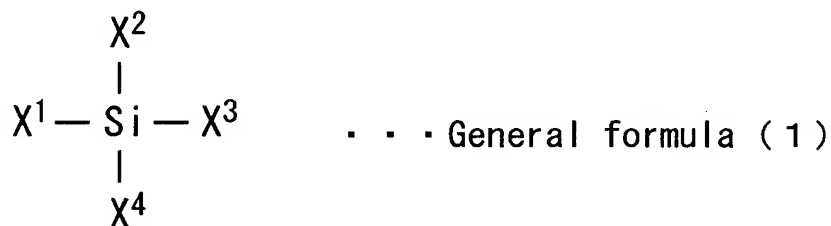
wherein said resin component includes a thermosetting resin, and said silane coupling agent is composed of a silane compound represented by general formula (1):



wherein at least one of substituents X^1 through X^4 is an alkoxy group, and wherein if one or more of the substituents X^1 through X^4 is a substituent other than alkoxy group, such substituent other than alkoxy group is a substituent that includes in its structure a functional group selected from the group consisting of epoxy ring, vinyl group, amino group, mercapto group and methyl group, and
wherein the metal chelate is microcapsulated.

16. (Currently Amended) An electric device comprising a semiconductor chip and a substrate, wherein an adhesive is disposed between said semiconductor chip and said substrate and is cured by heating, the adhesive including a resin component, a metal chelate, and a silane coupling agent,

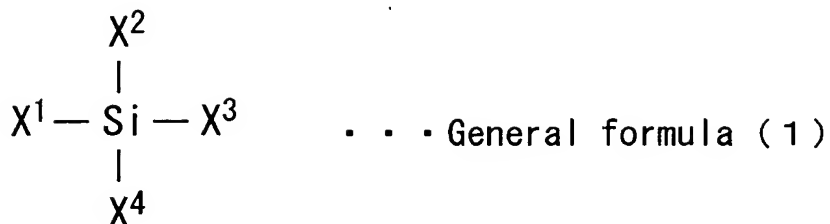
wherein said resin component includes a thermosetting resin and said silane coupling agent is composed of a silane compound represented by general formula (1):



wherein at least one of substituents X^1 through X^4 is an alkoxy group, and wherein if one or more of the substituents X^1 through X^4 is a substituent other than alkoxy group, such substituent other than alkoxy group is a substituent that includes in its structure a functional group selected from the group consisting of epoxy ring, vinyl group, amino group, mercapto group and methyl group.

17. (Currently Amended) An electric device comprising a glass substrate and a substrate, wherein an adhesive is disposed between said glass substrate and said substrate and is cured by heating, the adhesive including a resin component, a metal chelate, and a silane coupling agent,

wherein said resin component includes a thermosetting resin and said silane coupling agent is composed of a silane compound represented by general formula (1):



wherein at least one of substituents X^1 through X^4 is an alkoxy group, and wherein if one or more of the substituents X^1 through X^4 is a substituent other than alkoxy group, such substituent other than alkoxy group is a substituent that includes in its structure a functional group selected from the group consisting of epoxy ring, vinyl group, amino group, mercapto group and methyl group.

18. (Canceled).

19. (Currently Amended) The adhesive according to claim 1 ~~claim 18~~, wherein the metal chelate is a powder or liquid.

20. (Currently Amended) The adhesive according to claim 1 ~~claim 18~~, wherein microcapsules are formed as absorbent resin particles and dispersed in the adhesive.